2. IC pattern for U11-13 is to wide, rework leads to avoid shorting to Vias.
3. Vacuum bake P1 (F/N 3) at 800 for 72 hours.
5. Spotbond corners of U11-13, Q3 and U17 using F/N 16.
6. Do not install test headers.
7. Epoxy Q3 and Q4 to the board using F/N 17, epoxy layer to be as thin as possible.
8. Mounting dimensions specified starting location for epoxying fixed portion of header lead.
9. Measure unaltered capacitance prior to installation. Note polarity of the meter.
10. Parts to receive cursory visual inspection prior to installation.
12. Remove masking and masking removed prior to vacuum bake.
13. Cure at 250, ambient pressure for 8 hours.